

ABSTRACT:

Method of polishing a surface of copper or an alloy comprising mainly copper, magnetic head obtainable by means of said method, X-ray radiation-collimating element and X-ray radiation-reflecting element, both having a surface polished by means of the method, and polishing means suitable for use in the method.

Method of polishing a surface (5a) of copper or an alloy comprising mainly copper, in which a polishing means is moved across the surface while exerting a polishing pressure of approximately 500 g/cm² for obtaining a plane and smooth polished surface without any defects. A composition of a polishing component
5 comprising a colloidal suspension of SiO₂ particles having an average particle size of between 20 and 50 nm in an alkali solution, demineralised water and a chemical activator is used as a polishing means.

Fig. 3

This Sheet Has Been Replaced

